

# ETERNAL PHOTORESIST PRODUCT LIST

Product	Applications	Series	Thickness	Applicable Grades		
Dry Film Photoresist	Printed Circuit Boards (General Applications)	E	15 μm	7700	(E · T · P)	
				9300	(E · T · P)	
		APR	20 μm	9400	(E · T · P)	
				9500	(E · T · P)	
		HT	25 μm	300T	(E · T · P)	
				29 μm	100F	(E · T · P)
					100T	(E · T · P)
				34 μm	300	(E · P)
					38 μm	1900
				49 μm		2100
	Flexible Printed Circuit Boards , Packaging Boards (MCM · CSP · BGA · Flip Chip) , Ni/Gold Plating and ENIG Process , Wafer's Application	APR	15 μm		300T	(E · P)
		HP	20 μm	3600	(E · P · Au)	
			25 μm	3800	(E · P)	
		HQ	29 μm	6500	(ENIG)	
			38 μm	6300	(E · AE · P · AU)	
			49 μm	6200	(ENIG)	
		GA	75 μm	00	(B)	
			HP	100 μm	3600	(B)
		120 μm				
		BR	160 μm	40000	(B)	
240 μm						
Laser Direct Imaging (LDI)	UD	20 μm	900	(E · T · P)		
			900M	(E · T · P)		
	UDF	25 μm	7000	(E · P)		
			7100	(E · T · P)		
			7100M	(E · T · P)		
			7200	(E · T · P)		
			7200M	(E · T · P)		
			7200T	(E · T · P)		
	7300	49 μm	7300	(E · T · P)		
			7400	(E · T · P)		
Sand Blasting	TPR	50 μm	5200	(S)		
ITO Metal Etching	TPR	10 μm	2600	(ME)		
		15 μm		(ME)		
Dry Film Solder Mask	Flexible Printed Circuit Boards	DM	15 μm	DM8200	B(Black) Y(Yellow)	
	Printed Circuit Boards Ceramic Board (Passive Component)			25 μm	DM8500 DM5000	G(Green)
UV Marking Ink	Legend / Marking ink	ETERCURE	----	692		
					Dry Film Photosensitive Polyimid	Flexible Printed Circuit Boards
Ceramic Board (Passive Component)	10 μm	PIC-6500	Black			
		12 μm	EPD-3300	Amber		
20 μm						
	Vacuum Laminator	Printed Circuit Boards Packaging Boards Flexible Printed Circuit Boards Ceramic Board	CVP V	----	CVP-300	
CVP-600						
V-130	V-160					

## Notes:

T (Tent-and-Etch)

AE (Alkaline Etching)

ENIG (Electroless Nickel Immersion Gold)

P (Pattern Plating)

Au (Gold Plating)

ME(Metal Etching)

E (Print-and-Etch)

B (Bumping)

S (Sand Blasting)



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